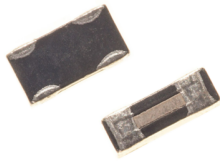


SCCM Series



Features

Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS, without distortion to high speed signal transmission.

Applications

MIPI, MHL serial interface in mobile device

Product Identification

SCCM xxxxxx HSxTL - XXX

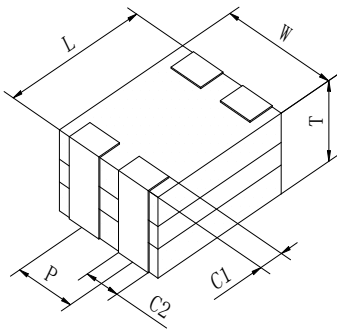
For example: SCCM121005HSHTL-900A

General Specifications

Test Frequency.....100MHz
 Parameters Test Temp..... 25℃
 Operation Temp..... -40℃ to +85℃
 (Including temperature Rise)
 Storage Temp.....0~40℃
 Storage Humidity.....<70% RH
 Resistance to Soldering Heat.....260℃ for 10 sec
 Temperature Rise.....40℃ Typ. at Rated Current

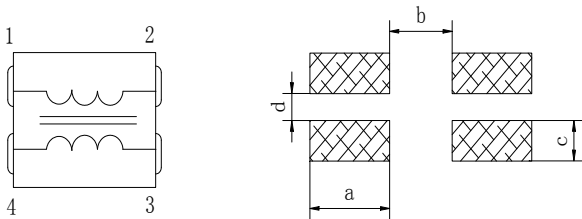
Shape And Dimensions

Dimensions In mm



TYPE	L	W	T	P	C1	C2	a	b	c	d
	±0.20	±0.20	±0.20	±0.20	±0.15	±0.20	Ref	Ref	Ref	Ref
121005	1.25	1.00	0.50	0.55	0.20	0.30	0.50	0.75	0.30	0.25

Electrical Schematic & PAD Layout



Standard Specifications

Stamp	Impedance (Ω)(±25%)	Test Frequency (MHz)	DCR (Ω) Max	Rated Current (mA) Max	Rated Voltage (V)	Insulation Resistance(MΩ) Min
SCCM121005HSHTL-900A	90	100	1.0	100	10	100
SCCM121005HSDTL-500A	50	100	1.5	100	10	100
SCCM121005HSDTL-670A	67	100	1.5	100	10	100
SCCM121005HSDTL-900A	90	100	1.5	100	10	100
SCCM121005HSDTL-900B	90	100	3.0	100	10	100
SCCM121005HSSTL-150A	15	100	0.8	100	10	100

*All the data listed in this catalogue are for reference only, JENG SHI reserves the right to alter or revise the specifications without prior notification.

*Beyond the above specification also can meet the special requirements. Need detailed content Please to the website query or contact us.

